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# DATA SHEET

**BF1211; BF1211R; BF1211WR**  
N-channel dual-gate MOS-FETs

Product specification

2003 Dec 16



# N-channel dual-gate MOS-FETs

# BF1211; BF1211R; BF1211WR

## FEATURES

- Short channel transistor with high forward transfer admittance to input capacitance ratio
- Low noise gain controlled amplifier
- Excellent low frequency noise performance
- Partly internal self-biasing circuit to ensure good cross-modulation performance during AGC and good DC stabilization.

## APPLICATIONS

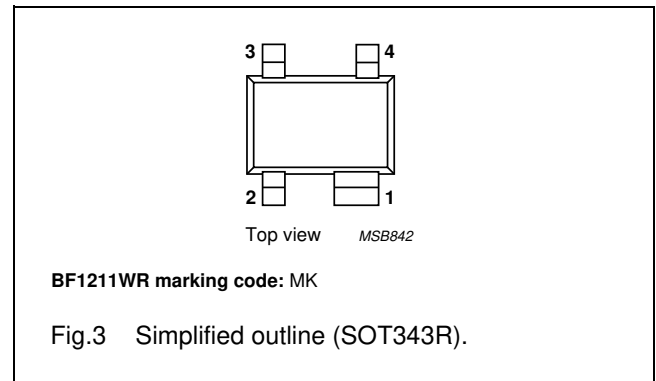
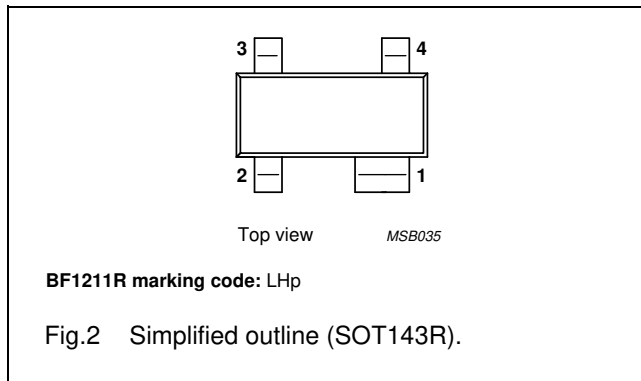
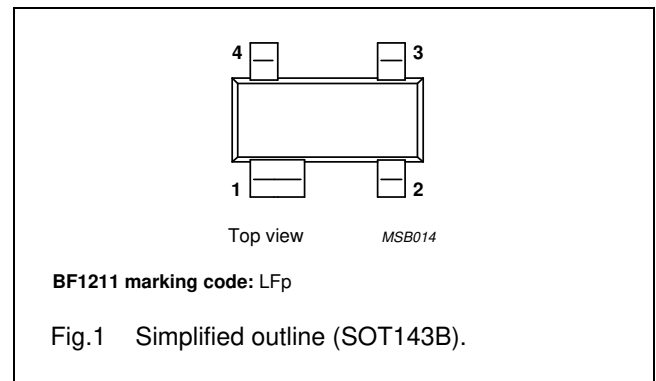
- Gain controlled low noise VHF and UHF amplifiers for 5 V digital and analog television tuner applications.

## DESCRIPTION

Enhancement type N-channel field-effect transistor with source and substrate interconnected. Integrated diodes between gates and source protect against excessive input voltage surges. The BF1211, BF1211R and BF1211WR are encapsulated in the SOT143B, SOT143R and SOT343R plastic packages respectively.

## PINNING

PIN	DESCRIPTION
1	source
2	drain
3	gate 2
4	gate 1



## QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$V_{DS}$	drain-source voltage		–	–	6	V
$I_D$	drain current		–	–	30	mA
$P_{tot}$	total power dissipation		–	–	180	mW
$ y_{fs} $	forward transfer admittance		25	30	40	mS
$C_{ig1-ss}$	input capacitance at gate 1		–	2.1	2.6	pF
$C_{rss}$	reverse transfer capacitance	$f = 1 \text{ MHz}$	–	15	30	fF
F	noise figure	$f = 400 \text{ MHz}$	–	0.9	1.6	dB
$X_{mod}$	cross-modulation	input level for $k = 1\%$ at 40 dB AGC	100	105	–	dB $\mu$ V
$T_j$	junction temperature		–	–	150	°C

## N-channel dual-gate MOS-FETs

## BF1211; BF1211R; BF1211WR

**CAUTION**

This product is supplied in anti-static packing to prevent damage caused by electrostatic discharge during transport and handling.

**ORDERING INFORMATION**

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
BF1211	–	plastic surface mounted package; 4 leads	SOT143B
BF1211R	–	plastic surface mounted package; reverse pinning; 4 leads	SOT143R
BF1211WR	–	plastic surface mounted package; reverse pinning; 4 leads	SOT343R

**LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$V_{DS}$	drain-source voltage		–	6	V
$I_D$	drain current (DC)		–	30	mA
$I_{G1}$	gate 1 current		–	$\pm 10$	mA
$I_{G2}$	gate 2 current		–	$\pm 10$	mA
$P_{tot}$	total power dissipation				
	BF1211; BF1211R	$T_s \leq 116\text{ °C}$ ; note 1	–	180	mW
	BF1211WR	$T_s \leq 122\text{ °C}$ ; note 1	–	180	mW
$T_{stg}$	storage temperature		–65	+150	°C
$T_j$	junction temperature		–	150	°C

**Note**

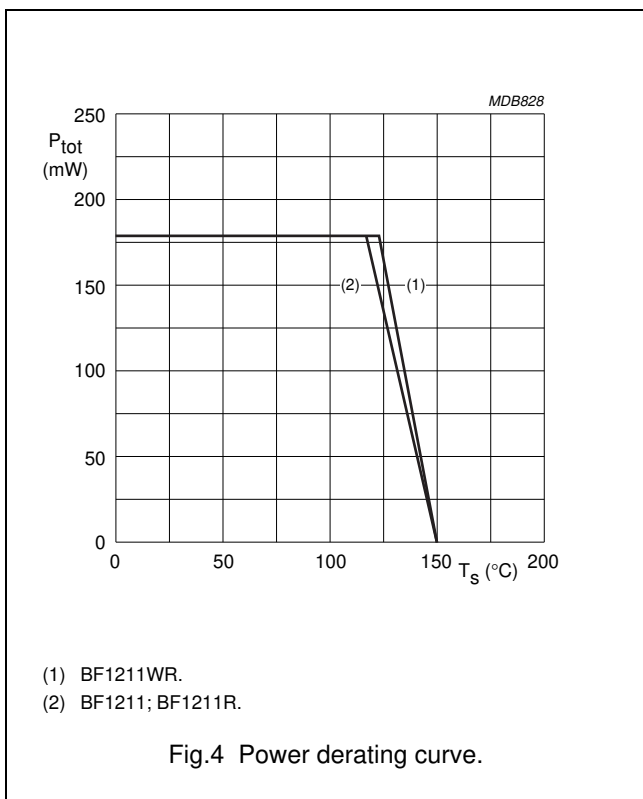
1.  $T_s$  is the temperature of the soldering point of the source lead.

**THERMAL CHARACTERISTICS**

SYMBOL	PARAMETER	VALUE	UNIT
$R_{th(j-s)}$	thermal resistance from junction to soldering point		
	BF1211; BF1211R	185	K/W
	BF1211WR	155	K/W

N-channel dual-gate MOS-FETs

BF1211; BF1211R; BF1211WR



**STATIC CHARACTERISTICS**

$T_j = 25\text{ }^\circ\text{C}$  unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$V_{(BR)DSS}$	drain-source breakdown voltage	$V_{G1-S} = V_{G2-S} = 0\text{ V}$ ; $I_D = 10\text{ }\mu\text{A}$	6	–	V
$V_{(BR)G1-SS}$	gate 1-source breakdown voltage	$V_{G2-S} = V_{DS} = 0\text{ V}$ ; $I_{G1-S} = 10\text{ mA}$	6	10	V
$V_{(BR)G2-SS}$	gate 2-source breakdown voltage	$V_{G1-S} = V_{DS} = 0\text{ V}$ ; $I_{G2-S} = 10\text{ mA}$	6	10	V
$V_{(F)S-G1}$	forward source-gate 1 voltage	$V_{G2-S} = V_{DS} = 0\text{ V}$ ; $I_{S-G1} = 10\text{ mA}$	0.5	1.5	V
$V_{(F)S-G2}$	forward source-gate 2 voltage	$V_{G1-S} = V_{DS} = 0\text{ V}$ ; $I_{S-G2} = 10\text{ mA}$	0.5	1.5	V
$V_{G1-S(th)}$	gate 1-source threshold voltage	$V_{G2-S} = 4\text{ V}$ ; $V_{DS} = 5\text{ V}$ ; $I_D = 100\text{ }\mu\text{A}$	0.3	1	V
$V_{G2-S(th)}$	gate 2-source threshold voltage	$V_{G1-S} = 5\text{ V}$ ; $V_{DS} = 5\text{ V}$ ; $I_D = 100\text{ }\mu\text{A}$	0.35	1	V
$I_{DSX}$	drain-source current	$V_{G2-S} = 4\text{ V}$ ; $V_{DS} = 5\text{ V}$ ; $R_{G1} = 75\text{ k}\Omega$ ; note 1	11	19	mA
$I_{G1-S}$	gate 1 cut-off current	$V_{G2-S} = V_{DS} = 0\text{ V}$ ; $V_{G1-S} = 5\text{ V}$	–	50	nA
$I_{G2-S}$	gate 2 cut-off current	$V_{G1-S} = V_{DS} = 0\text{ V}$ ; $V_{G2-S} = 4\text{ V}$	–	20	nA

**Note**

1.  $R_{G1}$  connects  $G_1$  to  $V_{GG} = 5\text{ V}$ .

## N-channel dual-gate MOS-FETs

## BF1211; BF1211R; BF1211WR

**DYNAMIC CHARACTERISTICS**Common source;  $T_{amb} = 25\text{ °C}$ ;  $V_{G2-S} = 4\text{ V}$ ;  $V_{DS} = 5\text{ V}$ ;  $I_D = 15\text{ mA}$ ; unless otherwise specified.

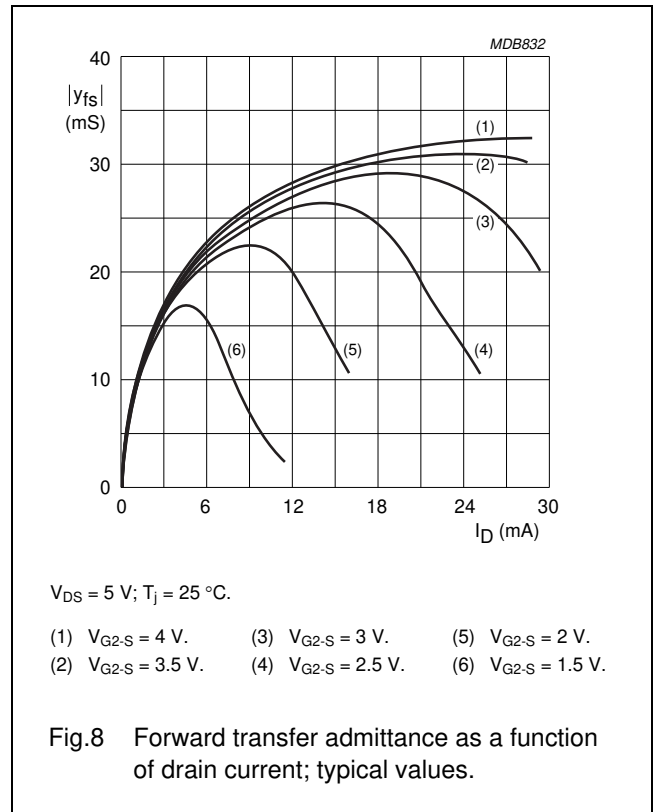
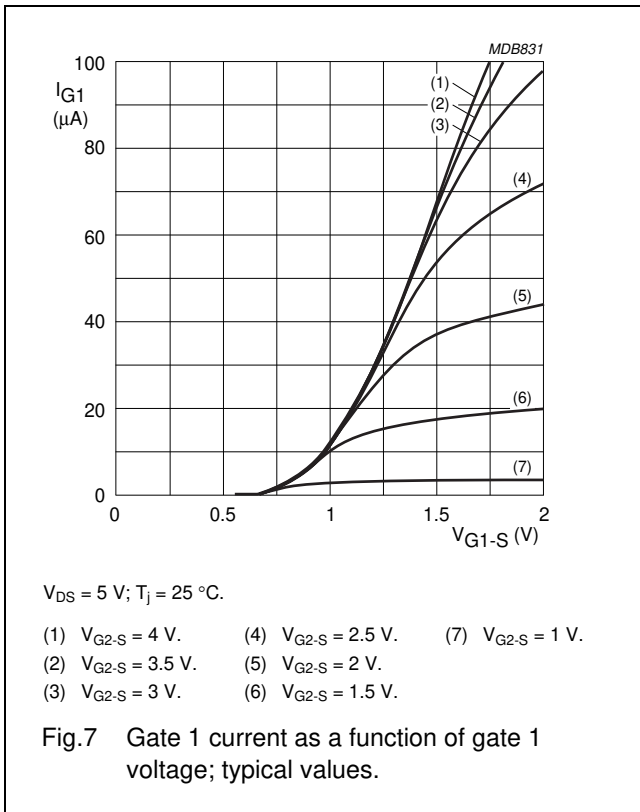
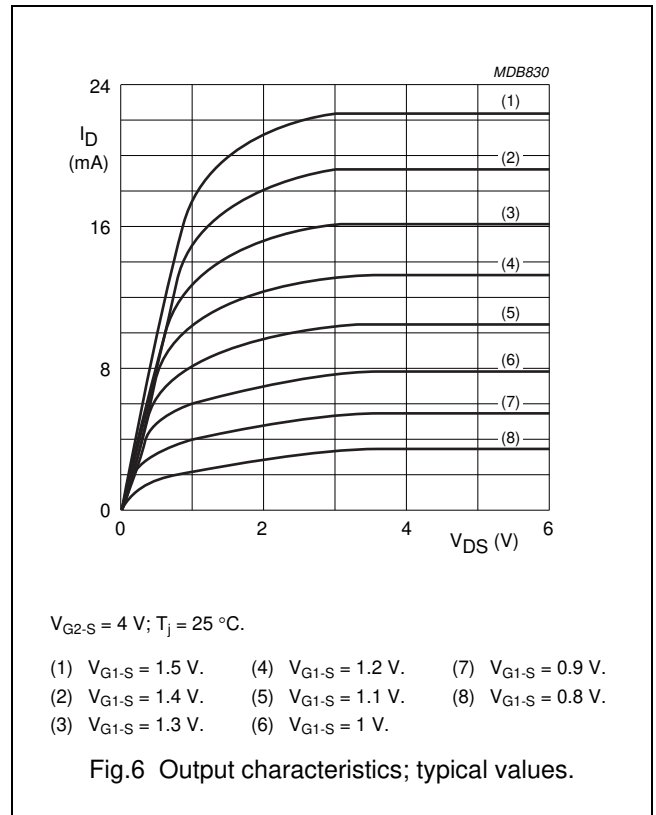
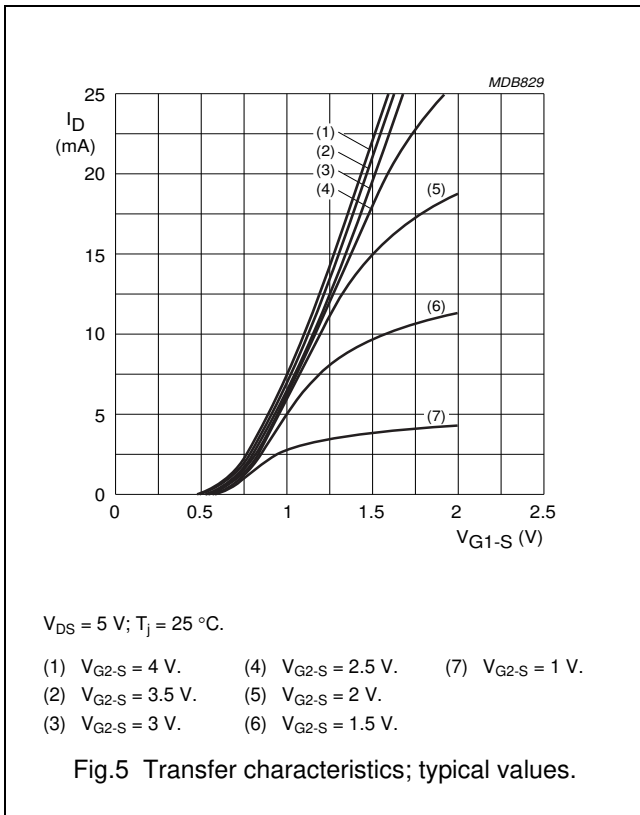
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$ y_{fs} $	forward transfer admittance	pulsed; $T_j = 25\text{ °C}$	25	30	40	mS
$C_{ig1-ss}$	input capacitance at gate 1	$f = 1\text{ MHz}$	–	2.1	2.6	pF
$C_{ig2-ss}$	input capacitance at gate 2	$f = 1\text{ MHz}$	–	1.1	–	pF
$C_{oss}$	output capacitance	$f = 1\text{ MHz}$	–	0.9	–	pF
$C_{rss}$	reverse transfer capacitance	$f = 1\text{ MHz}$	–	15	30	fF
F	noise figure	$f = 11\text{ MHz}$ ; $G_S = 20\text{ mS}$ ; $B_S = 0$	–	3.5	–	dB
		$f = 400\text{ MHz}$ ; $Y_S = Y_{S(opt)}$	–	0.9	1.6	dB
		$f = 800\text{ MHz}$ ; $Y_S = Y_{S(opt)}$	–	1.3	2	dB
$G_{tr}$	power gain	$f = 200\text{ MHz}$ ; $G_S = 2\text{ mS}$ ; $B_S = B_{S(opt)}$ ; $G_L = 0.5\text{ mS}$ ; $B_L = B_{L(opt)}$	–	34	–	dB
		$f = 400\text{ MHz}$ ; $G_S = 2\text{ mS}$ ; $B_S = B_{S(opt)}$ ; $G_L = 1\text{ mS}$ ; $B_L = B_{L(opt)}$	–	29	–	dB
		$f = 800\text{ MHz}$ ; $G_S = 3.3\text{ mS}$ ; $B_S = B_{S(opt)}$ ; $G_L = 1\text{ mS}$ ; $B_L = B_{L(opt)}$	–	24	–	dB
$X_{mod}$	cross-modulation	input level for $k = 1\%$ ; $f_w = 50\text{ MHz}$ ; $f_{unw} = 60\text{ MHz}$ ; note 1				
		at 0 dB AGC	90	–	–	dB $\mu$ V
		at 10 dB AGC	–	92	–	dB $\mu$ V
	at 40 dB AGC	100	105	–	dB $\mu$ V	

**Note**

1. Measured in test circuit Fig.21.

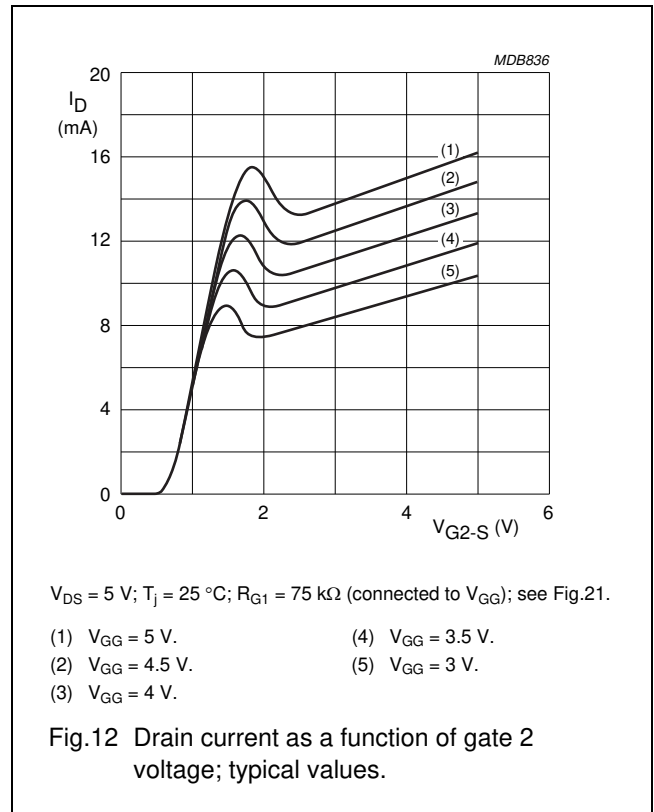
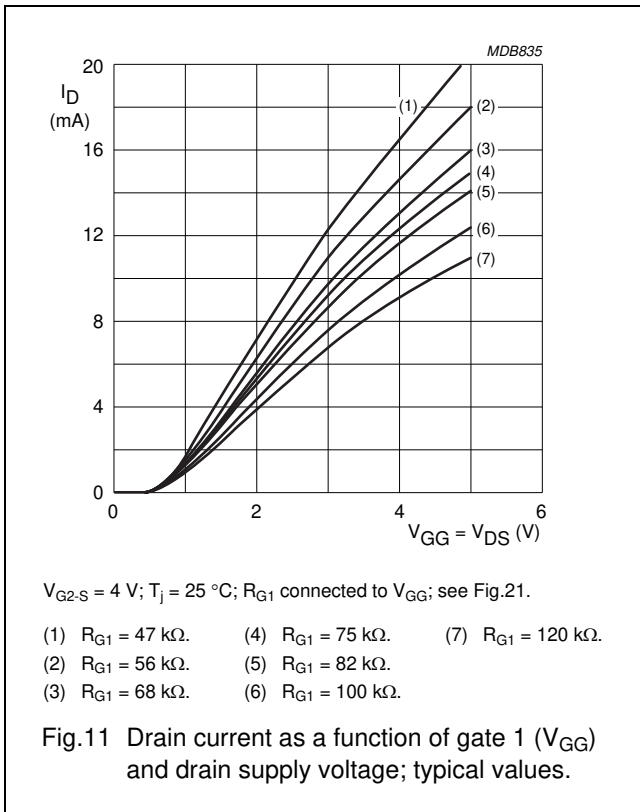
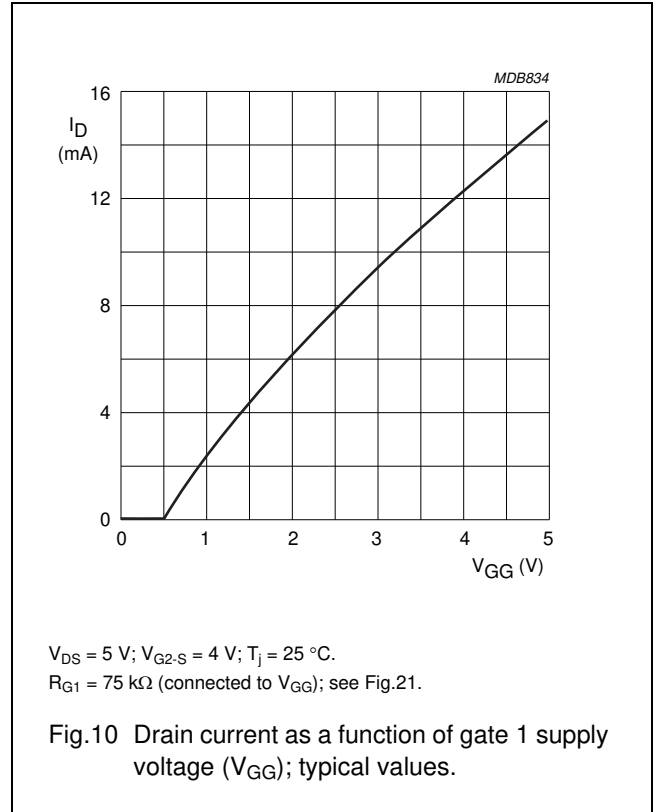
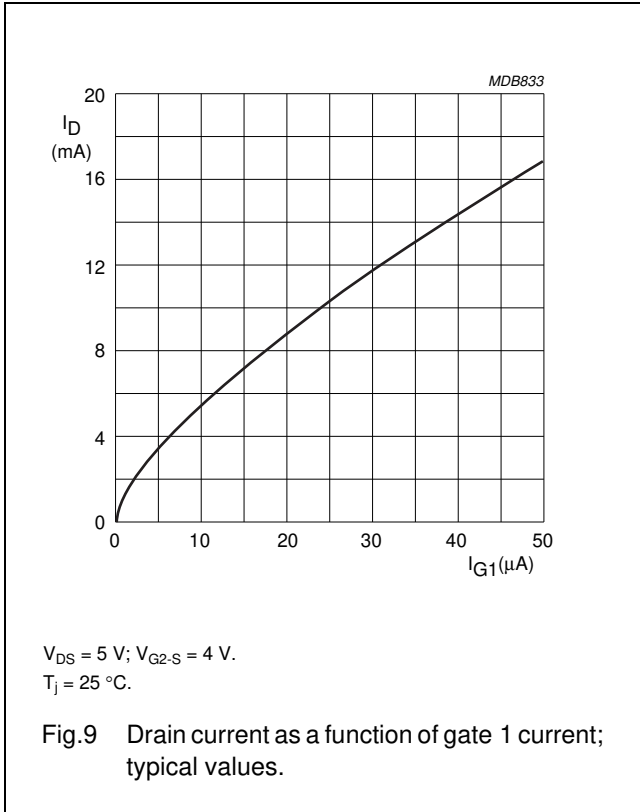
N-channel dual-gate MOS-FETs

BF1211; BF1211R; BF1211WR



N-channel dual-gate MOS-FETs

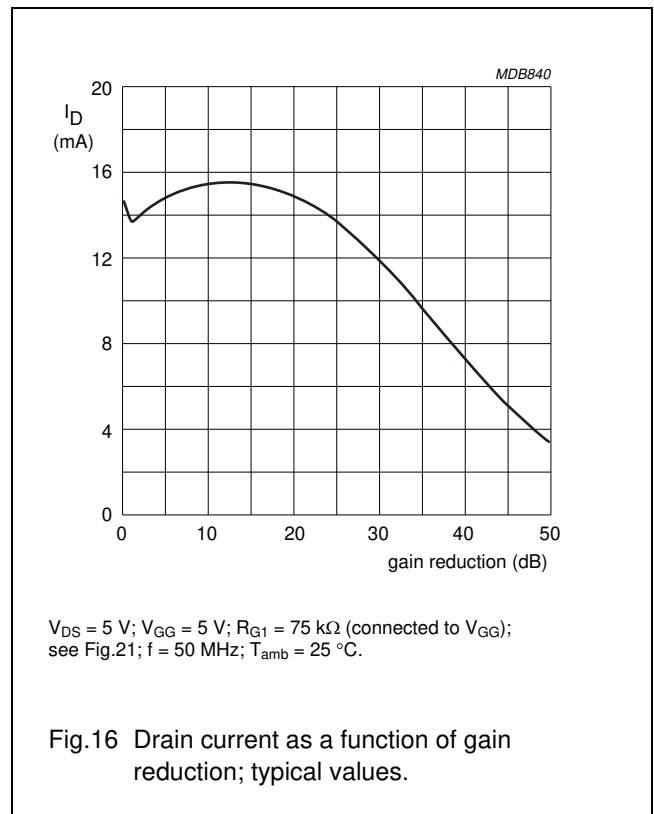
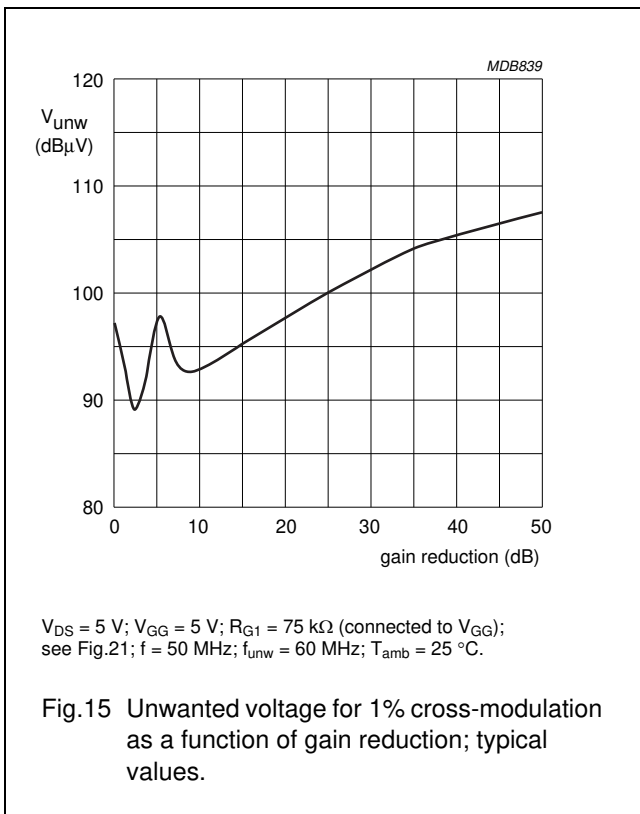
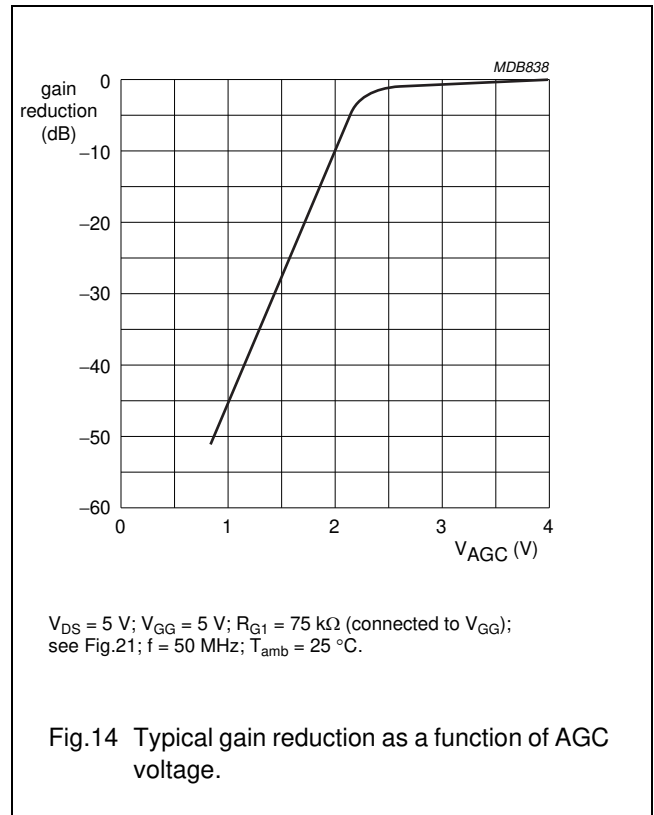
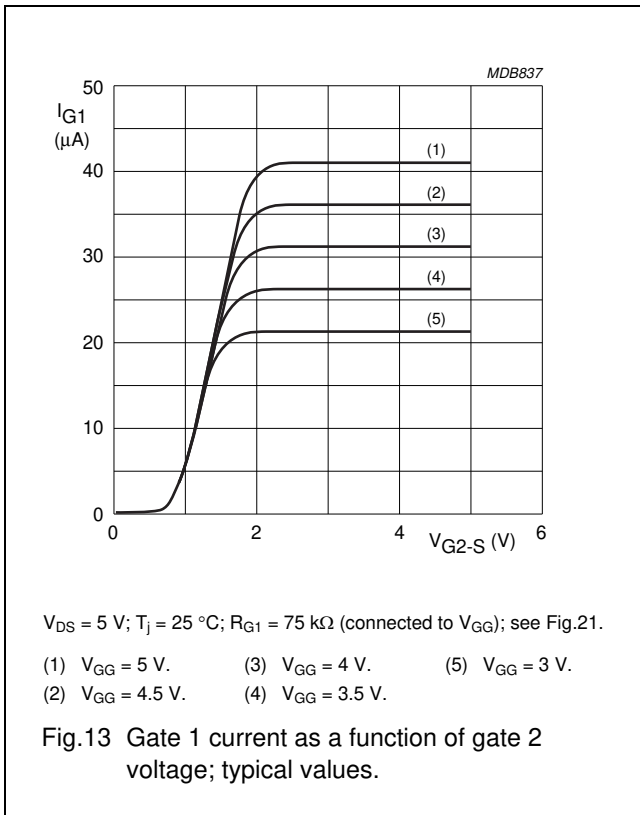
BF1211; BF1211R; BF1211WR





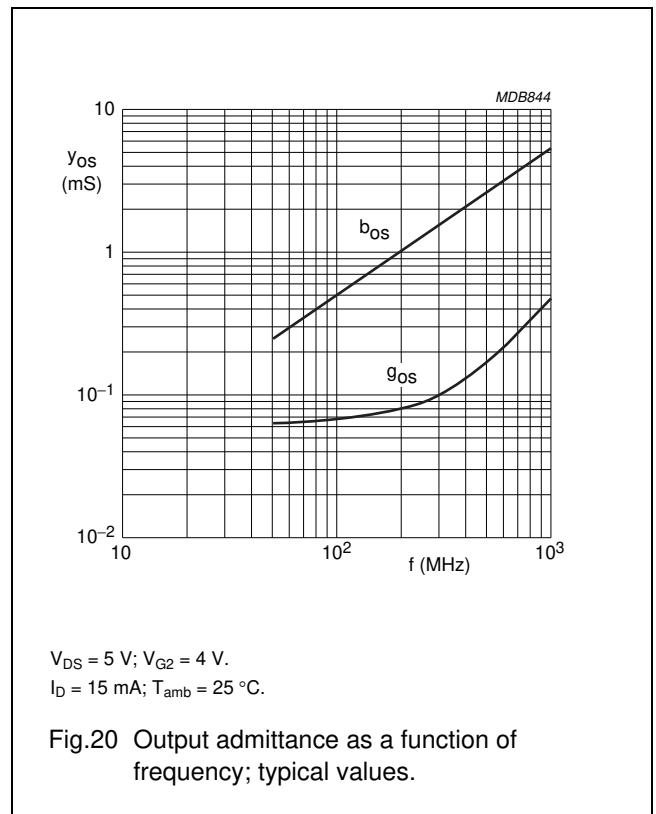
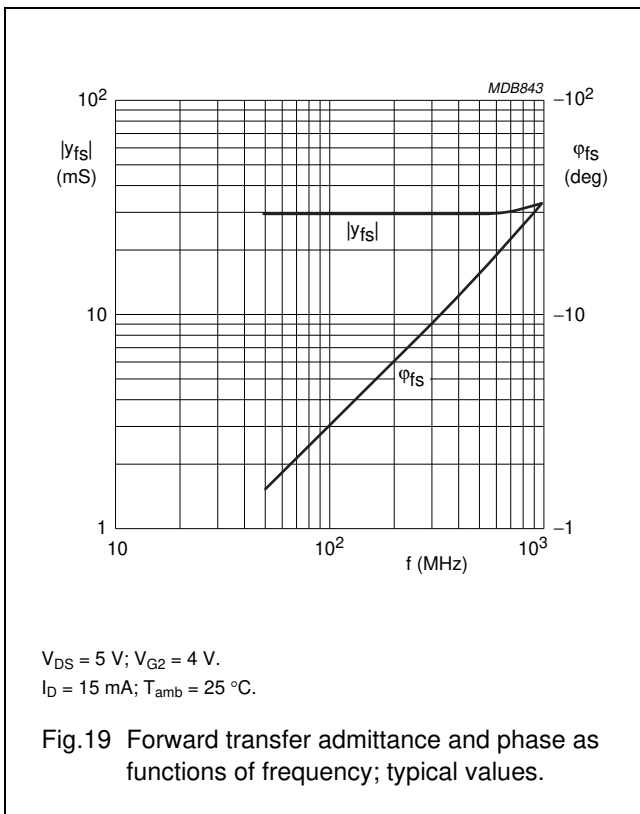
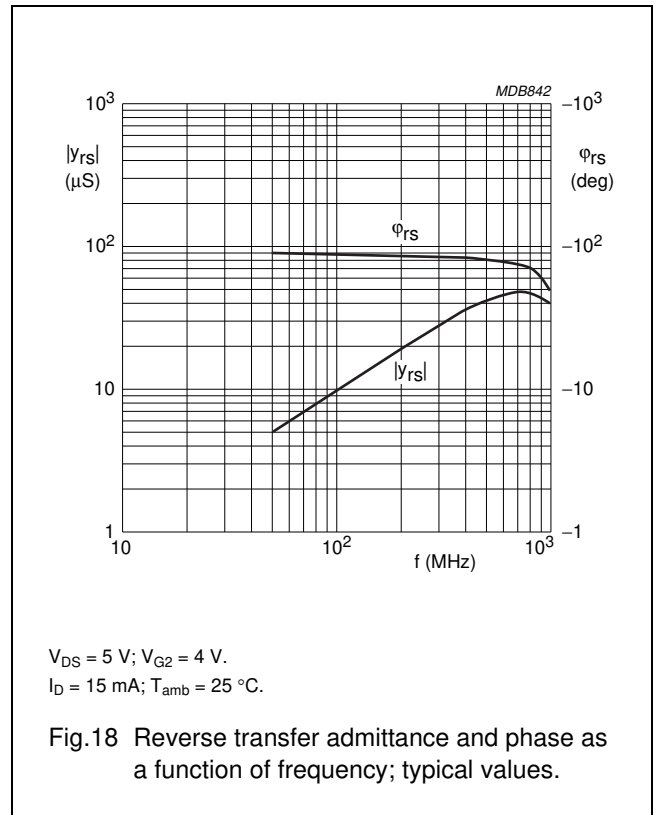
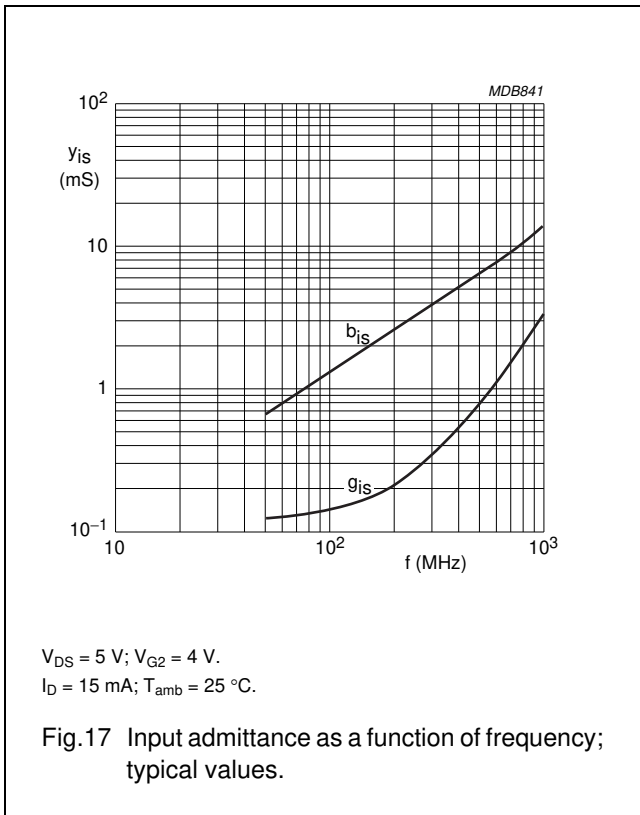
N-channel dual-gate MOS-FETs

BF1211; BF1211R; BF1211WR



N-channel dual-gate MOS-FETs

BF1211; BF1211R; BF1211WR



N-channel dual-gate MOS-FETs

BF1211; BF1211R; BF1211WR

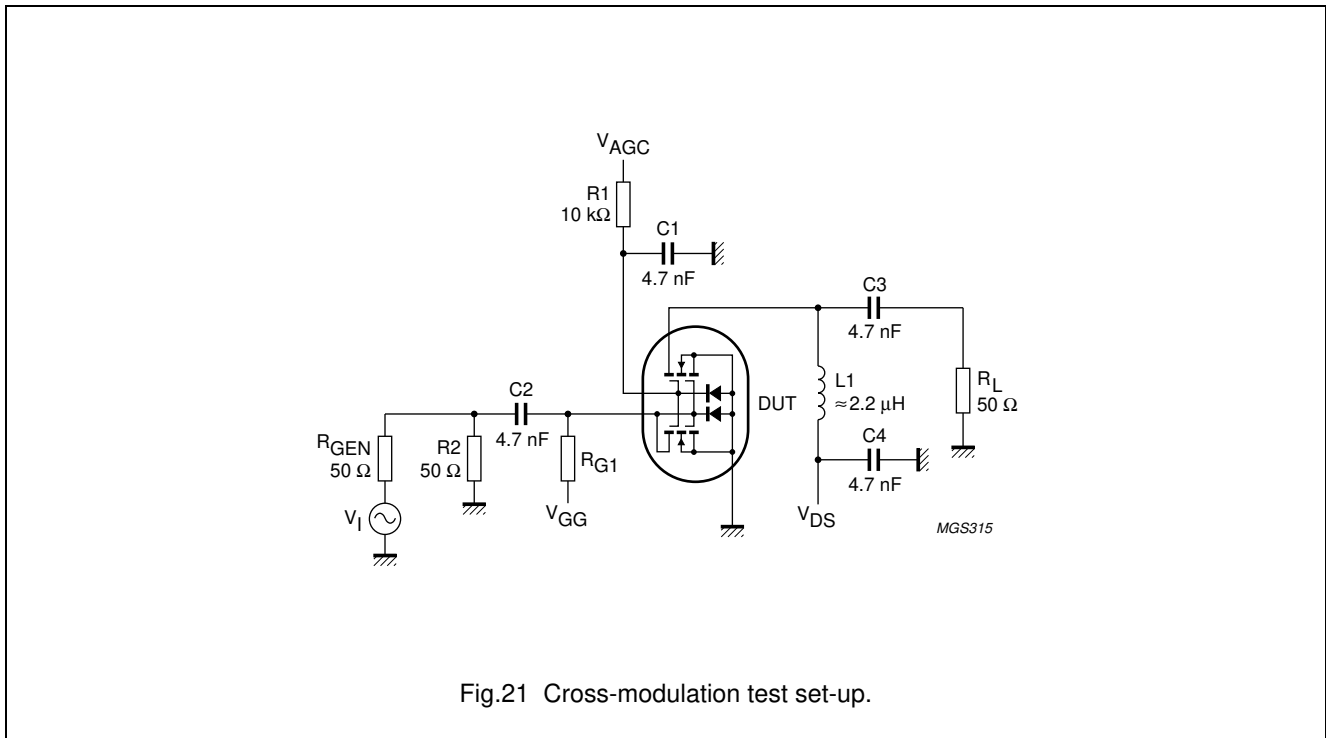


Fig.21 Cross-modulation test set-up.

**Table 1** Scattering parameters:  $V_{DS} = 5\text{ V}$ ;  $V_{G2-S} = 4\text{ V}$ ;  $I_D = 15\text{ mA}$ ;  $T_{amb} = 25\text{ }^\circ\text{C}$

f (MHz)	S <sub>11</sub>		S <sub>21</sub>		S <sub>12</sub>		S <sub>22</sub>	
	MAGNITUDE (ratio)	ANGLE (deg)	MAGNITUDE (ratio)	ANGLE (deg)	MAGNITUDE (ratio)	ANGLE (deg)	MAGNITUDE (ratio)	ANGLE (deg)
50	0.987	-3.86	2.928	175.8	0.0005	89.3	0.993	-1.58
100	0.985	-7.73	2.921	171.6	0.0010	86.9	0.993	-3.14
200	0.979	-15.25	2.807	163.2	0.0015	91.1	0.993	-6.31
300	0.965	-22.84	2.846	155.0	0.0028	77.4	0.988	-9.41
400	0.949	-30.15	2.784	146.7	0.0034	74.0	0.985	-12.48
500	0.929	-30.25	2.704	138.9	0.0037	71.4	0.981	-15.54
600	0.904	-44.24	2.639	130.9	0.0040	69.6	0.976	-18.59
700	0.876	-51.16	2.558	123.0	0.0039	69.0	0.971	-21.65
800	0.846	-58.16	2.486	115.1	0.0037	70.0	0.965	-24.27
900	0.816	-65.15	2.402	107.2	0.0032	74.5	0.960	-27.79
1000	0.791	-72.22	2.315	99.9	0.0028	87.1	0.956	-30.94

**Table 2** Noise data:  $V_{DS} = 5\text{ V}$ ;  $V_{G2-S} = 4\text{ V}$ ;  $I_D = 15\text{ mA}$ ;  $T_{amb} = 25\text{ }^\circ\text{C}$

f (MHz)	F <sub>min</sub> (dB)	Γ <sub>opt</sub>		R <sub>n</sub> (Ω)
		(ratio)	(deg)	
400	0.9	0.693	16.75	29.85
800	1.3	0.707	37.33	29.90

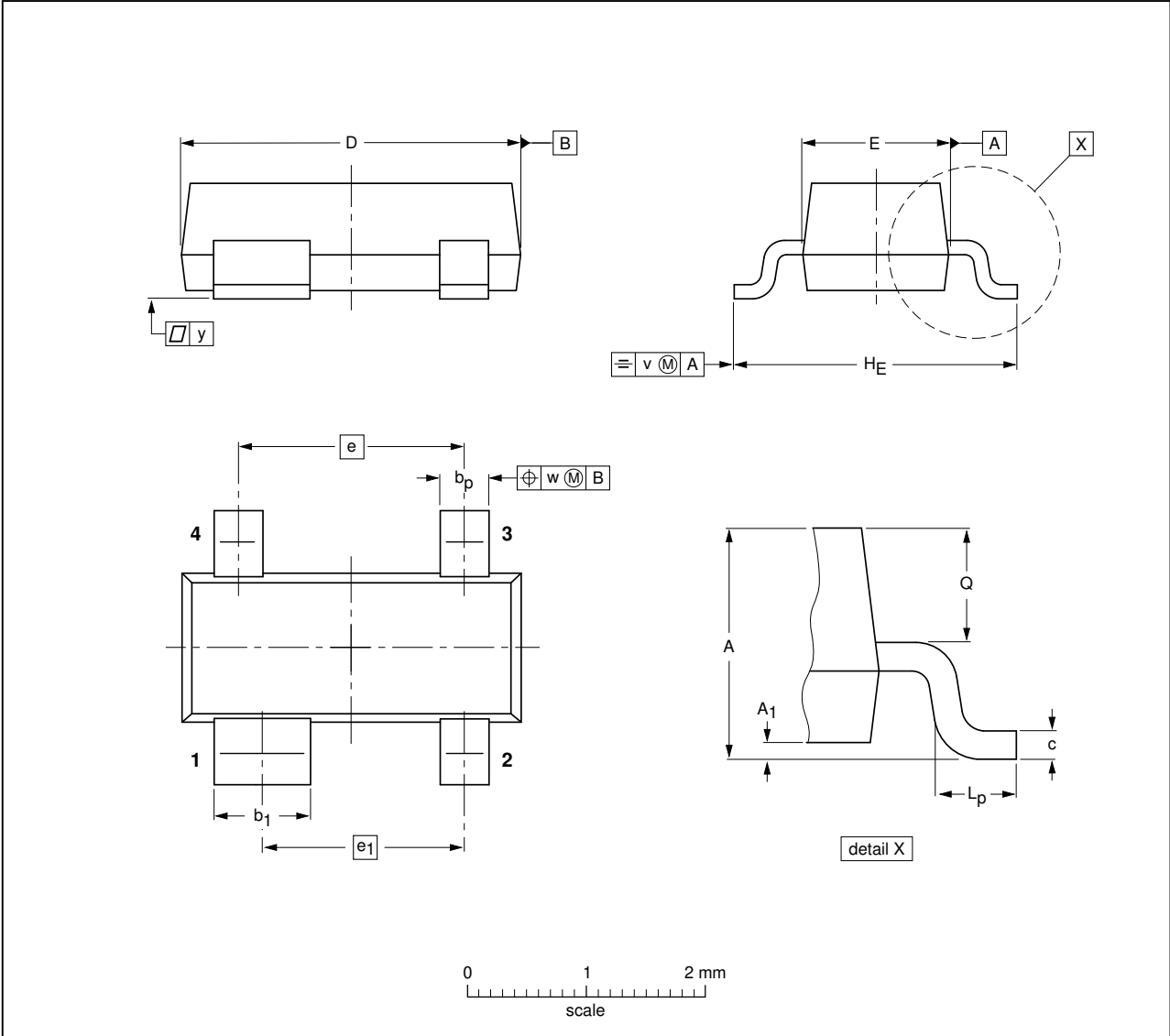
N-channel dual-gate MOS-FETs

BF1211; BF1211R; BF1211WR

PACKAGE OUTLINES

Plastic surface-mounted package; 4 leads

SOT143B



DIMENSIONS (mm are the original dimensions)

UNIT	A	A <sub>1</sub> max	b <sub>p</sub>	b <sub>1</sub>	c	D	E	e	e <sub>1</sub>	H <sub>E</sub>	L <sub>p</sub>	Q	v	w	y
mm	1.1 0.9	0.1	0.48 0.38	0.88 0.78	0.15 0.09	3.0 2.8	1.4 1.2	1.9	1.7	2.5 2.1	0.45 0.15	0.55 0.45	0.2	0.1	0.1

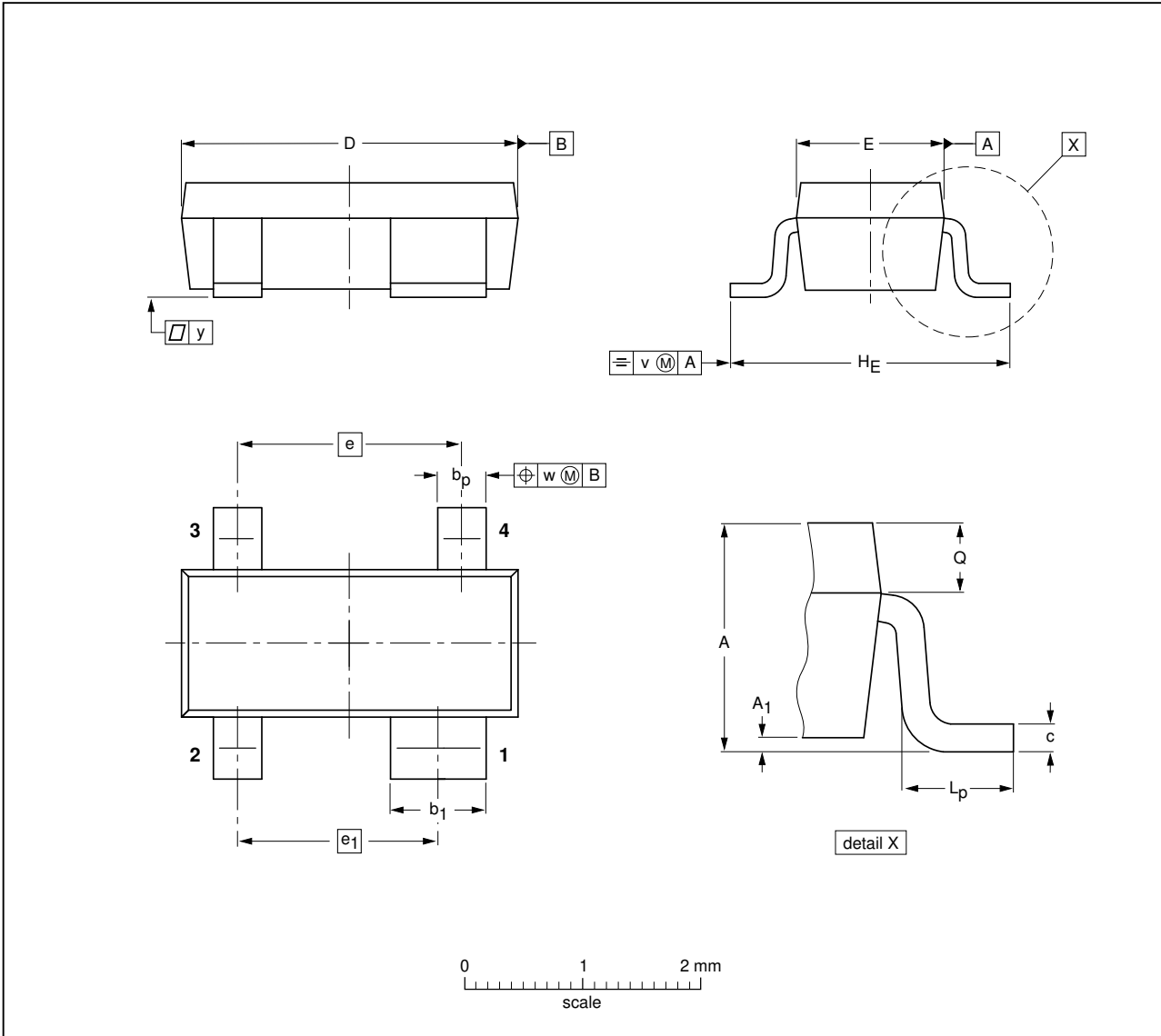
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	IEC	JEDEC	JEITA			
SOT143B						04-11-16 06-03-16

N-channel dual-gate MOS-FETs

BF1211; BF1211R; BF1211WR

Plastic surface-mounted package; reverse pinning; 4 leads

SOT143R



DIMENSIONS (mm are the original dimensions)

UNIT	A	A <sub>1</sub> max	b <sub>p</sub>	b <sub>1</sub>	c	D	E	e	e <sub>1</sub>	H <sub>E</sub>	L <sub>p</sub>	Q	v	w	y
mm	1.1 0.9	0.1	0.48 0.38	0.88 0.78	0.15 0.09	3.0 2.8	1.4 1.2	1.9	1.7	2.5 2.1	0.55 0.25	0.45 0.25	0.2	0.1	0.1

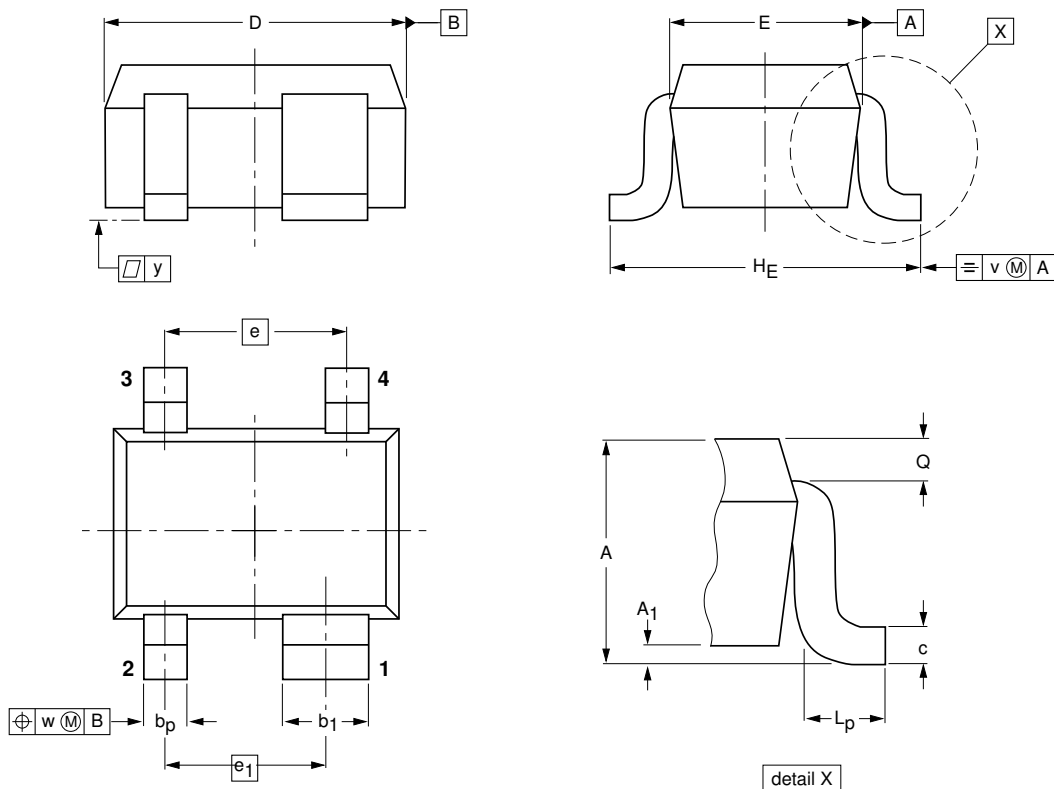
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SOT143R			SC-61AA			04-11-16 06-03-16

N-channel dual-gate MOS-FETs

BF1211; BF1211R; BF1211WR

Plastic surface-mounted package; reverse pinning; 4 leads

SOT343R



DIMENSIONS (mm are the original dimensions)

UNIT	A	A <sub>1</sub> max	b <sub>p</sub>	b <sub>1</sub>	c	D	E	e	e <sub>1</sub>	H <sub>E</sub>	L <sub>p</sub>	Q	v	w	y
mm	1.1 0.8	0.1	0.4 0.3	0.7 0.5	0.25 0.10	2.2 1.8	1.35 1.15	1.3	1.15	2.2 2.0	0.45 0.15	0.23 0.13	0.2	0.2	0.1

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ		
SOT343R					97-05-21 06-03-16

## N-channel dual-gate MOS-FETs

## BF1211; BF1211R; BF1211WR

## DATA SHEET STATUS

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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## N-channel dual-gate MOS-FETs

## BF1211; BF1211R; BF1211WR

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# ***NXP Semiconductors***

***provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise***

## **Customer notification**

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

## **Contact information**

For additional information please visit: <http://www.nxp.com>

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